



BCP5610Q

80V NPN MEDIUM POWER TRANSISTOR IN SOT223

Description

This Bipolar Junction Transistor (BJT) is designed to meet the stringent requirements of Automotive Applications.

Features

- BV_{CEO} > 80V
- I_C = 1A High Continuous Collector Current
- I_{CM} = 2A Peak Pulse Current
- 2W Power Dissipation
- Low Saturation Voltage V_{CE(SAT)} < 500mV @ 0.5A
- Complementary PNP Type: BCP5316Q
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Applications

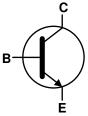
- Medium Power Switching or Amplification Applications
- AF Driver and Output Stages

Mechanical Data

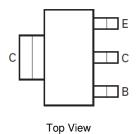
- Case: SOT223
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish—Matte Tin Plated Leads.
 Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.112 grams (Approximate)







Device Symbol



Pin-Out

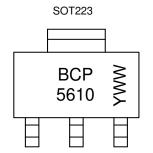
Ordering Information (Note 5)

Part Number	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
BCP5610QTA	Automotive	BCP 5610	7	12	1000
BCP5610QTC	Automotive	BCP 5610	13	12	4000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to https://www.diodes.com/quality/.
- 5. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information



BCP 5610 = Product Type Marking Code YWW = Date Code Marking Y or \overline{Y} = Last Digit of Year (ex: 9 = 2019) WW or $\overline{W}W$ = Week Code (01 to 53)



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	100	V
Collector-Emitter Voltage	V _{CEO}	80	V
Emitter-Base Voltage	V _{EBO}	5	V
Continuous Collector Current	Ic	1	Δ.
Peak Pulse Collector Current	I _{CM}	2	A
Continuous Base Current	I _B	100	mA
Peak Pulse Base Current	Івм	200	IIIA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Power Dissipation	(Note 6)	P _D	2	W
Thermal Resistance, Junction to Ambient	(Note 6)	$R_{ heta JA}$	62	°C /W
Thermal Resistance, Junction to Leads (Note 7)		$R_{ heta JL}$	19.4	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C	

ESD Ratings (Note 8)

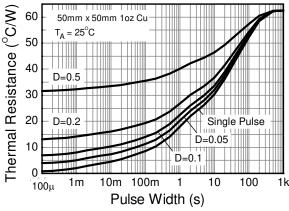
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge—Human Body Model	ESD HBM	4000	V	3A
Electrostatic Discharge—Machine Model	ESD MM	400	V	С

Notes:

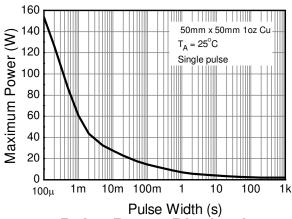
^{6.} For a device mounted with the collector lead on 50mm × 50mm 1oz copper that is on a single-sided 1.6mm FR-4 PCB; device is measured under still air conditions whilst operating in steady-state.
7. Thermal resistance is from junction to solder-point (at the end of the collector lead).
8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.



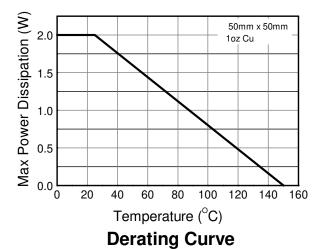
Thermal Characteristics and Derating Information



Transient Thermal Impedance



Pulse Power Dissipation



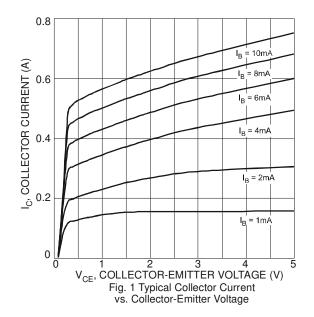


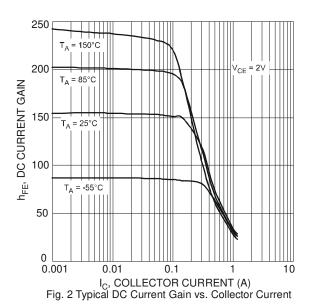
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	100	-	_	V	$I_C = 100\mu A$
Collector-Emitter Breakdown Voltage (Note 9)	BV _{CEO}	80	_		V	$I_C = 10mA$
Emitter-Base Breakdown Voltage	BV _{EBO}	5		l	V	$I_E = 10\mu A$
Collector Cut-Off Current	I _{CBO}			0.1 20	μΑ	V _{CB} = 30V V _{CB} = 30V, T _A = +150°C
Emitter Cut-Off Current	I _{EBO}	1	-	20	nA	$V_{EB} = 4V$
Static Forward Current Transfer Ratio (Note 9)	h _{FE}	25 63 25	-	160	_	$I_{C} = 5mA, V_{CE} = 2V$ $I_{C} = 150mA, V_{CE} = 2V$ $I_{C} = 500mA, V_{CE} = 2V$
Collector-Emitter Saturation Voltage (Note 9)	V _{CE(SAT)}		_	0.5	V	$I_C = 500 \text{mA}, I_B = 50 \text{mA}$
Base-Emitter Turn-On Voltage (Note 9)	V _{BE(ON)}	l	1	1.0	V	$I_C = 500 \text{mA}, V_{CE} = 2V$
Transition Frequency	f⊤	100	150		MHz	$I_C = 50 \text{mA}, V_{CE} = 10 \text{V}$ f = 100MHz
Output Capacitance	C _{OBO}	1	1	25	pF	$V_{CB} = 10V$, $f = 1MHz$

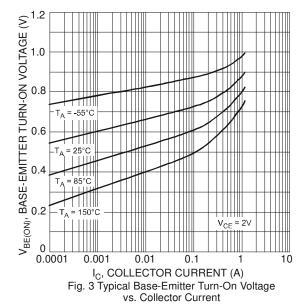
Note:

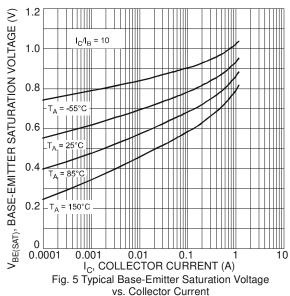
^{9.} Measured under pulsed conditions. Pulse width \leq 300 μ s. Duty cycle \leq 2%.

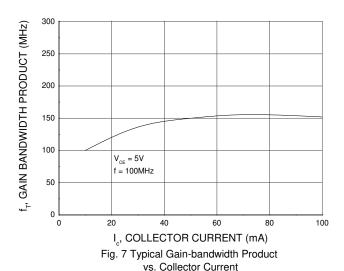












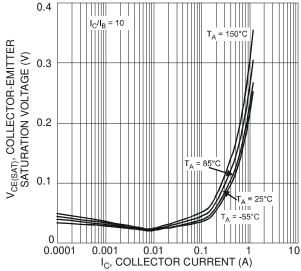


Fig. 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

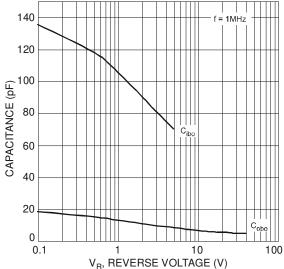


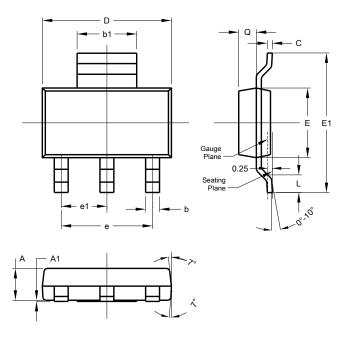
Fig. 6 Typical Capacitance Characteristics



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT223

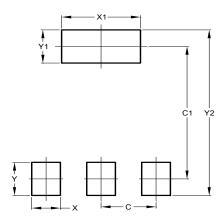


SOT223					
Dim	Min	Max	Тур		
Α	1.55	1.65	1.60		
A1	0.010	0.15	0.05		
b	0.60	0.80	0.70		
b1	2.90	3.10	3.00		
С	0.20	0.30	0.25		
D	6.45	6.55	6.50		
Е	3.45	3.55	3.50		
E1	6.90	7.10	7.00		
е	-	-	4.60		
e1	-	-	2.30		
L	0.85	1.05	0.95		
Q	0.84	0.94	0.89		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT223



Dimensions	Value (in mm)
С	2.30
C1	6.40
X	1.20
X1	3.30
Υ	1.60
Y1	1.60
Y2	8.00



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